



PRODUCT CHANGE NOTIFICATION (PCN) # 121115-002

IXYS COLORADO HAS FOUND IT NECESSARY TO IMPLEMENT A PRODUCT CHANGE. THIS NOTIFICATION IS TO INFORM YOU OF THE CHANGE WHICH MAY AFFECT YOUR PRODUCTS.

SUBJECT: Relocation of gate bond wires on DE-Series devices (all DE-150, DE-275, DE-275X2, DE-375 and DE-475 devices) from the Lead Frame to the DCB substrate		DOC NUMBER: PCN 121115-002
TYPE OF DOCUMENT: COMMERCIAL CUSTOMER NOTIFICATION – FOR POSTING TO IXYS COLORADO WEB SITE.		REVISION: N/A
<input type="checkbox"/> BILL OF MATERIAL <input checked="" type="checkbox"/> DRAWING	<input checked="" type="checkbox"/> MANUFACTURING INSTRUCTION <input type="checkbox"/> OTHER	REVISION DATE: December 2015
DESCRIPTION OF CHANGE: An approved assembly subcontractor for IXYS Colorado, will change the location of the bond wires from bonding to the device Lead Frame to the device DCB (Direct Copper Bond) substrate. This change will improve the overall reliability of the devices, and will be phased in on a lot by lot basis.		
REASON FOR CHANGE: <input type="checkbox"/> STANDARDIZATION <input type="checkbox"/> MARKET DEMAND <input type="checkbox"/> TECHNICAL REQUIREMENT <input type="checkbox"/> UPGRADE <input checked="" type="checkbox"/> CORRECTIVE ACTION <input type="checkbox"/> MANAGEMENT DECISION <input type="checkbox"/> PRODUCT SAFETY <input type="checkbox"/> OTHER ** <p align="center">**Product discontinuation/consolidation</p>		
REMARKS:		
PCN APPROVAL: PCN Initiator: Gilbert Bates Product Engineer Reviewed By: Steve Krausse General Manager		Date: December 11, 2015 Date: December 11, 2015